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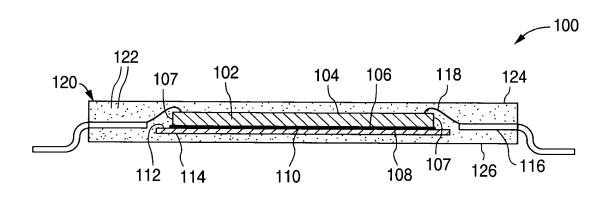


FIG. 1 (Prior Art) 122 - 100 102 124 104 118 107 120 208 116 126 **2**04 106 107 206 202

FIG. 2

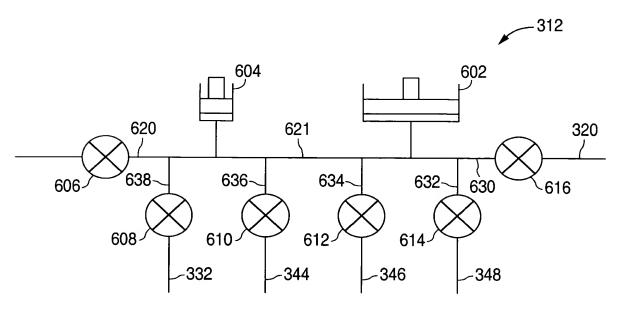
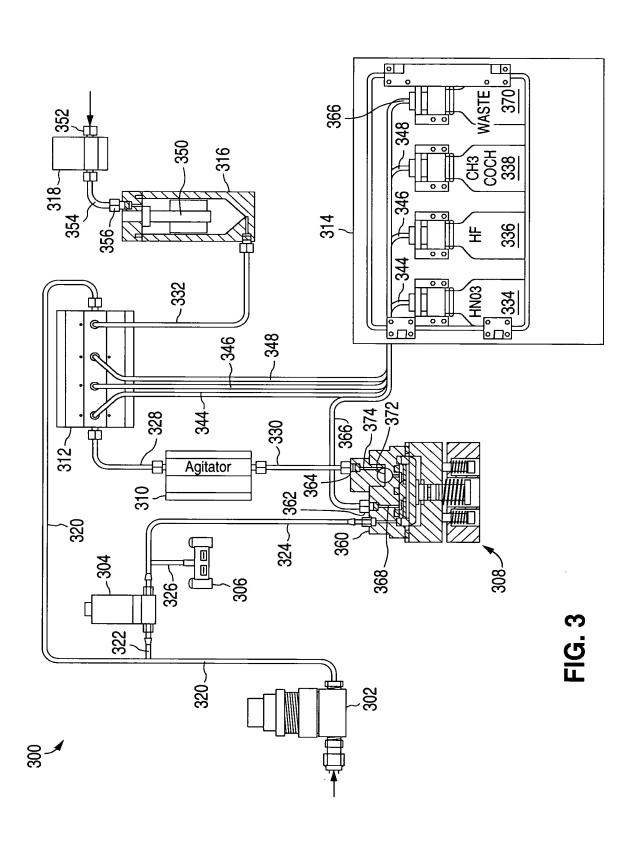


FIG. 7







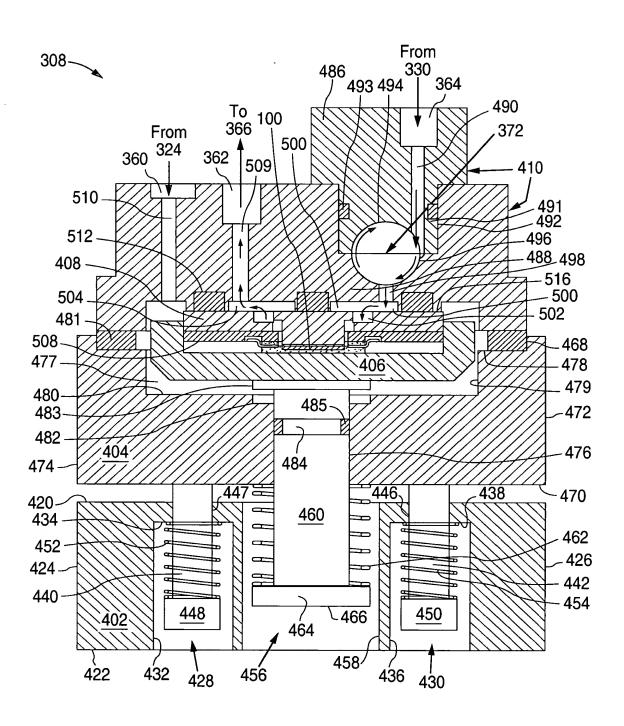
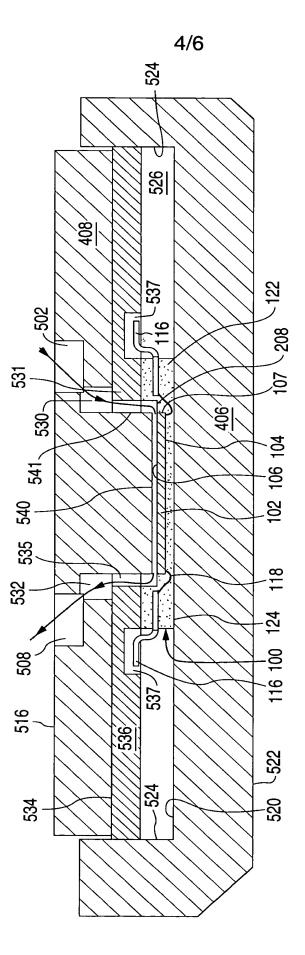


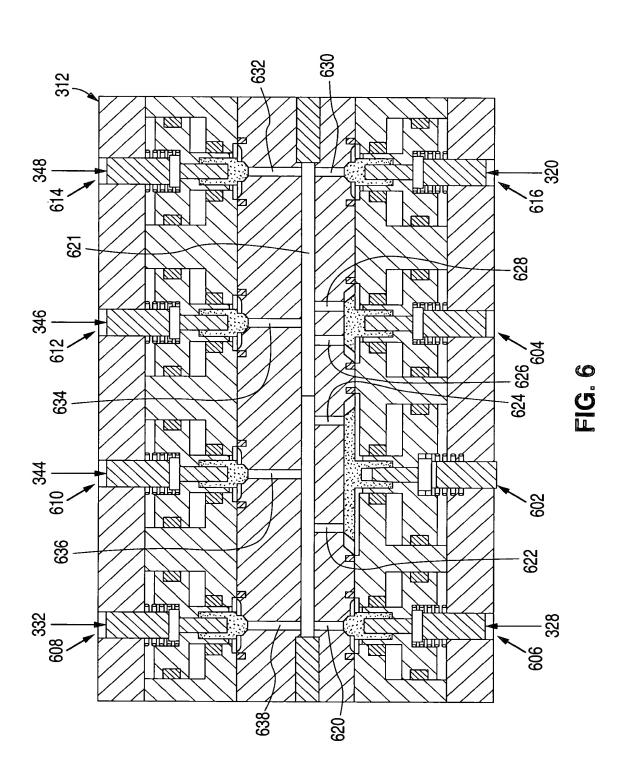
FIG. 4



Title: Method and Apparatus for Etching a Semiconductor Die Inventor: Kirk Martin Application No.: 09/902,931









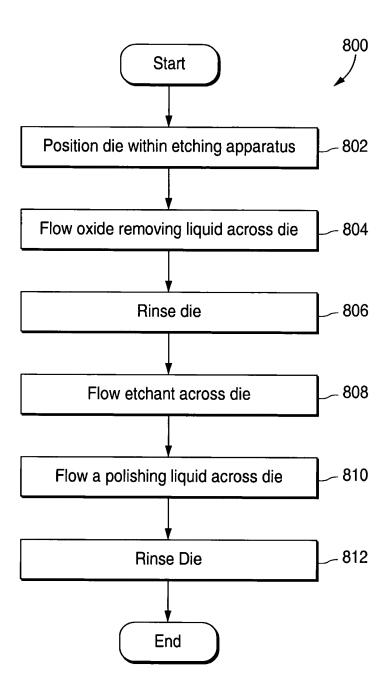


FIG. 8